



Chip Scale Schottky from Diodes Incorporated Doubles Power Density

Plano, Texas – June 6, 2013 – Diodes Incorporated (Nasdaq: DIOD), a leading global manufacturer and supplier of high-quality application specific standard products within the broad discrete, logic and analog semiconductor markets, today announced its first wafer-level, chip-scale packaged Schottky diode. The SDM0230CSP provides smartphone and tablet designs with an alternative to miniature DFN0603-packaged devices, while offering twice the power density in the same PCB footprint.

In the X3-WLCUS0603-3 solder pad package, the 30V, 0.2A SDM0230CSP Schottky diode has a typical thermal resistance of just 261°C/W. This is around half that of the DFN0603 package so power dissipation is doubled in switching, reverse-blocking and rectification circuits.

Utilizing 70% less board space than the industry-standard DFN1006 and SOD923 packaged Schottkys, the 0.18mm² footprint SDM0230CSP is well suited to high-density design. Additionally, its 0.3mm off board profile is 25% thinner, benefiting ultra-thin portable products.

The Schottky's low maximum forward voltage of just 0.5V for a forward current of 0.2A, combined with a typical low leakage current of only 1.5mA at a reverse voltage of 30V, means it minimizes power losses, thus extending battery life. For further information, visit the Company's website at www.diodes.com.

About Diodes Incorporated

Diodes Incorporated (Nasdaq: DIOD), a Standard and Poor's SmallCap 600 and Russell 3000 Index company, is a leading global manufacturer and supplier of high-quality application specific standard products within the broad discrete, logic and analog semiconductor markets. Diodes serves the consumer

electronics, computing, communications, industrial, and automotive markets. Diodes' products include diodes, rectifiers, transistors, MOSFETs, protection devices, functional specific arrays, single gate logic, amplifiers and comparators, Hall-effect and temperature sensors; power management devices, including LED drivers, AC-DC converters and controllers, DC-DC switching and linear voltage regulators, and voltage references along with special function devices, such as USB power switches, load switches, voltage supervisors, and motor controllers. Diodes' corporate headquarters, logistics center, and Americas' sales office are located in Plano, Texas. Design, marketing, and engineering centers are located in Plano; San Jose, California; Taipei, Taiwan; Manchester, England; and Neuhaus, Germany. Diodes' wafer fabrication facilities are located in Kansas City, Missouri and Manchester, with two more located in Shanghai, China. In addition, two assembly-test facilities are located in Shanghai; two are located in Chengdu, China, with one in Neuhaus and one in Taipei. Additional engineering, sales, warehouse, and logistics offices are located in Fort Worth, Texas; Taipei; Hong Kong; Manchester; Shanghai; Shenzhen, China; Seongnam-si, South Korea; Suwon, South Korea; Tokyo, Japan; and Munich, Germany, with support offices throughout the world. For further information, including SEC filings, visit Diodes' website at <http://www.diodes.com>.

###

Company Contact:

Diodes Incorporated
Francis Tang
VP, Worldwide Discrete Products
P: 972-987-3900
E: pressinquiries@diodes.com

Investor Relations Contact:

Shelton Group
Leanne K. Sievers
EVP, Investor Relations
P: 949-224-3874
E: lsievers@sheltongroup.com